

Please amend Claims 1, 3 and 4 as follows:

1. (Currently Amended) A mounting structure of a wireless module, comprising:

a circuit board having electrical components including semiconductor components mounted on anits upper surface;

a cover attached to the circuit board while covering the electrical components; and

a motherboard for mounting the circuit board thereon,

wherein the cover has a box-shaped cover portion and at least one leg portion projected downward from the cover portion,

wherein at least one first through holes for inserting the at least one leg portions isare provided in the circuit board, and at least one second through holes for inserting the at least one leg portions isare provided in the motherboard, and

wherein the at least one leg portions isare soldered to the circuit board and the motherboard at the at least one first and second through holes or at a positions close to the at least one first and second through holes in a state wherein the at least one leg portions isare inserted into the at least one first and second through holes, respectively.

2. (Original) The mounting structure of a wireless module according to claim 1, wherein the circuit board overlaps~~is put on~~ the motherboard to~~overlap each other~~.

3. (Currently Amended) The mounting structure of a wireless module according to claim 1, wherein conductors are provided on the walls of the at least one first and second through holes, and the at least one leg portions isare soldered to the conductors.

4. (Currently Amended) The mounting structure of a wireless module according to claim 1, wherein the at least one leg portions extend in a straight-line shape.